

Special Issue

Technological Advances and Industrial Applications in Intelligent Manufacturing

Message from the Guest Editor

We are pleased to invite you to contribute to a Special Issue of the *Journal of Manufacturing and Materials Processing* on "Technological Advances and Industrial Applications in Intelligent Manufacturing". This collection focuses on the transformative integration of additive manufacturing and inverse problem-solving within intelligent manufacturing. This Special Issue invites cutting-edge research, theoretical insights, and practical implementations that address the following:

- Innovative solutions to inverse problems in design and production;
- Material characterization, properties, and simulation techniques;
- Non-parametric and structural optimization;
- Multiphysics design and industrial case studies;
- AI integration in intelligent manufacturing;
- Applications of nanomaterials in additive manufacturing.

Guest Editor

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Deadline for manuscript submissions

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About the Journal

Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (JMMP) (ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to *JMMP*.

Editor-in-Chief

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Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.2 days after submission; acceptance to publication is undertaken in 3.6 days (median values for papers published in this journal in the first half of 2025).